



PRESS RELEASE

BE Semiconductor Industries Announces 2019 Second Quarter Results Release, Conference Call and Webcast Date

Duiven, the Netherlands, July 18, 2019 - BE Semiconductor Industries N.V. ("the Company" or "Beside"), (Euronext Amsterdam: BESI; OTC: BESIY, Nasdaq International Designation), a leading manufacturer of assembly equipment for the semiconductor industry, will release results for the second quarter ended June 30, 2019, on Thursday, July 25, 2019 at 7.00 a.m. CET (1.00 a.m. EST).

Beside will host a conference call and audio webcast (log on via www.besi.com) to discuss its results for the second quarter ended June 30, 2019, on Thursday, July 25, 2019 at 4.00 p.m. CET (10.00 a.m. EST). The teleconference dial-in number is (+31) 20 531 5851. The audio webcast will remain available on www.besi.com.

About Beside

Beside is a leading supplier of semiconductor assembly equipment for the global semiconductor and electronics industries offering high levels of accuracy, productivity and reliability at a low cost of ownership. The Company develops leading edge assembly processes and equipment for leadframe, substrate and wafer level packaging applications in a wide range of end-user markets including electronics, mobile internet, cloud server, computing, automotive, industrial, LED and solar energy. Customers are primarily leading semiconductor manufacturers, assembly subcontractors and electronics and industrial companies. Beside's ordinary shares are listed on Euronext Amsterdam (symbol: BESI). Its Level 1 ADRs are listed on the OTC markets (symbol: BESIY Nasdaq International Designation) and its headquarters are located in Duiven, the Netherlands. For more information, please visit our website at www.besi.com.

Contacts:

Richard Blickman, CEO
Cor te Hennepe, SVP Finance
Tel. (31) 26 319 4500
investor.relations@besi.com

IR Contact Europe:

Frank Jansen
CFF Communications
Tel. (31) 20 575 4024
besi@cffcommunications.nl